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5 V Differential PECL to TTL Translator

Description

The MC10ELT/100ELT21 is a differential PECL to TTL translator. Because PECL (Positive ECL) levels are used, only +5 V and ground are required. The small outline 8-lead package and the single gate of the ELT21 makes it ideal for those applications where space, performance and low power are at a premium.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The 100 Series contains temperature compensation.

Features

- 3.5 ns Typical Propagation Delay
- 24 mA TTL Output
- Flow Through Pinouts
- Operating Range: $V_{CC} = 4.75 \text{ V}$ to 5.25 V with GND = 0 V
- Q Output Will Default LOW with Inputs Left Open or < 1.3 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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MARKING DIAGRAMS*



SOIC-8 D SUFFIX CASE 751











H = MC10 K = MC100

A = Assembly Location L = Wafer Lot

L = water

Y = Year

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

^{*}For additional marking information, refer to Application Note AND8002/D.

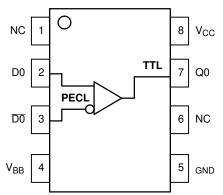


Figure 1. 8-Lead Pinout and Logic Diagram (Top View)

Table 1. PIN DESCRIPTION

Pin	Function
Q0	TTL Outputs
D0, DO	PECL Differential Outputs
V _{BB}	Reference Voltage Output
V _{CC}	Positive Supply
GND	Ground
NC	No Connect

Table 2. ATTRIBUTES

Characteris	Value				
Internal Input Pulldown Resistor		50 kΩ			
Internal Input Pullup Resistor		N/A			
ESD Protection	Human Body Model	> 2 kV			
Moisture Sensitivity, Indefinite Time	Out of Drypack (Note 1)	Pb-Free Pkg			
	SOIC-8 TSSOP-8	Level 1 Level 3			
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in			
Transistor Count		81 Devices			
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test					

^{1.} For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Power Supply	GND = 0 V		7	V
V _{IN}	PECL Input Voltage	GND = 0 V	$V_I \leq V_{CC}$	0 to 6	V
I _{BB}	V _{BB} Sink/Source			± 0.5	mA
TA	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 SOIC-8	190 130	°C/W
θJC	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44	°C/W
θЈА	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
T _{sol}	Wave Solder Pb-Free	<2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. 10ELT SERIES PECL INPUT DC CHARACTERISTICS $V_{CC} = 5.0 \text{ V}$; GND = 0.0 V (Note 2)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V _{IH}	Input HIGH Voltage (Single-Ended)	3770		4110	3870		4190	3930		4265	mV
V _{IL}	Input LOW Voltage (Single-Ended)	3050		3500	3050		3520	3050		3555	mV
V _{BB}	Output Voltage Reference	3.57		3.7	3.65		3.75	3.69		3.81	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.2		5.0	2.2		5.0	2.2		5.0	V
I _{IH}	Input HIGH Current			255			175			175	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.3			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- 2. Output parameters vary 1:1 with V_{CC} . V_{CC} can vary \pm 0.25 V.
- 3. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC}.

Table 5. 100ELT SERIES PECL INPUT DC CHARACTERISTICS V_{CC} = 5.0 V; GND = 0.0 V (Note 4)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V _{IH}	Input HIGH Voltage (Single-Ended)	3835		4120	3835		4120	3835		4120	mV
V _{IL}	Input LOW Voltage (Single-Ended)	3190		3525	3190		3525	3190		3525	mV
V _{BB}	Output Voltage Reference	3.62		3.74	3.62		3.74	3.62		3.745	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5)	2.2		5.0	2.2		5.0	2.2		5.0	V
I _{IH}	Input HIGH Current			255			175			175	μΑ
I _{IL}	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- $\begin{array}{l} \text{4. Input parameters vary 1:1 with V_{CC}. V_{CC} can vary ± 0.25 V.} \\ \text{5. V_{IHCMR} min varies 1:1 with GND, V_{IHCMR} max varies 1:1 with V_{CC}.} \\ \end{array}$

Table 6. TTL OUTPUT DC CHARACTERISTICS $V_{CC} = 4.75 \text{ V}$ to 5.25 V; $T_A = -40 ^{\circ}\text{C}$ to $85 ^{\circ}\text{C}$)

Symbol	Characteristic Condition		Min	Тур	Max	Unit
V _{OH}	Output HIGH Voltage	$I_{OH} = -3.0 \text{ mA}$	2.4		(Note 6)	V
V _{OL}	Output LOW Voltage	I _{OL} = 24 mA			0.5	V
I _{CCH}	Power Supply Current			20	29	mA
I _{CCL}	Power Supply Current			22	32	mA
I _{OS}	Output Short Circuit Current		-150		-60	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

6. Maximum level is V_{CC} – 0.7 by design.

AC CHARACTERISTICS $V_{CC} = 4.75 \text{ V}$ to 5.25 V; GND = 0.0 V (Note 7)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency					100					MHz
t _{JITTER}	Random Clock Jitter (RMS)					35					ps
t _{PLH}	Propagation Delay @ 1.5 V	2.0		5.5	2.0		5.5	2.0		5.5	ns
t _{PHL}	Propagation Delay @ 1.5 V	2.0		5.5	2.0		5.5	2.0		5.5	ns
V _{PP}	Input Swing (Note 8)	200		1000	200		1000	200		1000	mV
t _r /t _f	Output Rise/Fall Time (10–90%)					750					ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- 7. $R_L = 500 \Omega$ to GND and $C_L = 20 pF$ to GND. Refer to Figure 2.
- 8. $V_{PP}(min)$ is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of ≈ 40 .

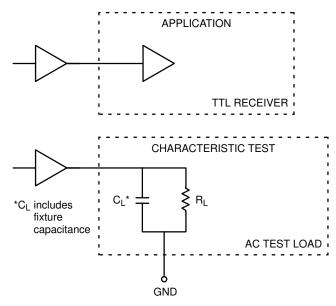


Figure 2. TTL Output Loading Used for Device Evaluation

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10ELT21DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC10ELT21DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC10ELT21DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC10ELT21DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100ELT21DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100ELT21DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100ELT21DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100ELT21DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

 $\textbf{AN1503/D} \qquad - \quad \text{ECLinPS} \ ^{\text{\tiny{TM}}} \ \text{I/O SPiCE Modeling Kit}$

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

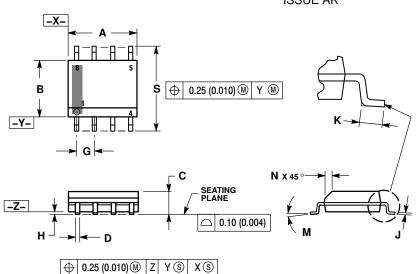
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AK**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.

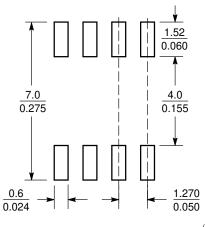
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

 6. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751–07.
- STANDARD IS 751-07.

	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.053	0.069		
D	0.33	0.51	0.013	0.020		
G	1.27	7 BSC	0.050 BSC			
Н	0.10	0.25	0.004	0.010		
J	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
М	0 °	8 °	0 °	8 °		
N	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228	0.244		

SOLDERING FOOTPRINT*

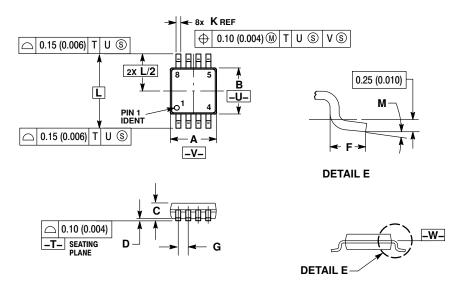


 $\left(\frac{\text{mm}}{\text{inches}}\right)$ SCALE 6:1

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** CASE 948R-02 **ISSUE A**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
 - Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH.
 PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- (U.000) FER 310E.

 DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	2.90	3.10	0.114	0.122		
В	2.90	3.10	0.114	0.122		
С	0.80	1.10	0.031	0.043		
D	0.05	0.15	0.002	0.006		
F	0.40	0.70	0.016	0.028		
G	0.65	BSC	0.026 BSC			
K	0.25	0.40	0.010	0.016		
L	4.90 BSC		0.193 BSC			
М	00	6 0	n٥	60		

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